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020732-97.668 (7493)

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#### Section L. (The Claims)

- 1. (Previously Presented) A cleaning composition including an active cleaning combination (ACC), wherein said ACC consists of a quaternary base in combination with at least one of alkali and alkaline earth base and said cleaning composition is useful for removing photoresist and/or sacrificial anti-reflective coating (SARC) materials from a substrate having such material(s) thereon.
- 2. (Original) The cleaning composition of dlaim 1, which is devoid of hydroxylamine therein.
- 3. (Cancelled)
- 4. (Previously Presented) The cleaning composition of claim 1, comprising the following components:
  - 0.1 40.0 weight % organic quaternary base;
  - 0.01-5 weight % alkali or alkaline earth base;
  - 0-80 weight % solvent(s) and/or amine(s);
  - 0-5 weight % surfactant;
  - 0-10 weight % chelator/passivation agent; and
  - 0-98 weight % water,

wherein percentages of the components are percentages by weight, based on total weight of the composition, and wherein the total of the weight percentages of such components of the composition does not exceed 100 weight %.

- 5. (Previously Presented) The cleaning composition of claim 1, including at least one additional ingredient selected from the group consisting of stabilizers, dispersants, anti-oxidants, fillers, penetration agents, adjuvants, additives, and excipients.
- 6. (Previously Presented) The cleaning composition of claim 1, comprising the following components:
  - 2-15 weight % organic quaternary base;
  - ~0.01-2 weight % alkali or alkaline earth base;
  - 0-50 weight % solvent(s) and/or amine(s);

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~0.01-2 weight % surfactant;

0 - 5 weight % chelator/passivation agent; and

40 - 95 weight % water,

wherein percentages of the components are percentages by weight, based on total weight of the composition, and wherein the total of the weight percentages of such components of the composition does not exceed 100 weight %.

7. (Previously Presented) A cleaning composition selected from the group consisting of Formulations A-C<sup>2</sup>, wherein all percentages are by weight, based on the total weight of the formulation:

#### Formulation A

5.36% benzyltrimethylammonium hydroxide
0.28% potassium hydroxide
3.0% 4-methylmorpholine N-oxide
0.30% polyoxyethylene(150) dinonylphenyl ether
0.08% 2-mercaptobenzimidazole
91.0% water

#### Formulation B

5.36% benzyltrimethylammonium hydroxide
0.28% potassium hydroxide
3.0% 4-methylmorpholine N-oxide
0.30% polyoxyethylene(150) dinonylphenyl ether
0.20% 5-amino-1,3,4-thiadiazole-2-thiol
90.86% water

#### Formulation C

3.60% benzyltrimethylammonium hydroxide
0.27% potassium hydroxide
3.5% 4-methylmospholine N-oxide
15.0% 4-(3-aminopropyl)mospholine
0.30% polyoxyethylene(150) dinonylphenyl ether
0.08% 2-mercaptobenzimidazole
77.25% water

#### Formulation D

5.36% benzyltrimethylammonium hydroxide 0.28% potassium hydroxide 20.0% dimethyl sulfoxide 0.08% 2-mercaptobenzimidazole 74.28% water

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#### Formulation E

5.36% benzyltrimethylammonium hydroxide

0.28% potassium hydroxide

10.0% tetramethylene sulfone

0.30% oxirane, methyl-, polymer with oxirane, ether with 2,2'-(oxidoimino)bis(ethanol) (2:1), N(-3(C9-11-isoalkyloxy)propyl)derivatives C<sub>10</sub>-rich

0.08% 2-mercaptobenzimidazole

83.98% water

#### Formulation F

5.36% benzyltrimethylammonium hydroxide

0.28% potassium hydroxide

10.0% di(ethyleneglycol)butyl ether

10.0% 2-(2-dimethylamino)ethoxy)ethanol

0.30% oxirane, methyl-, polymer with oxirane, ether with 2,2'-(oxidoimino)bis(ethanol) (2:1), N(-3(C9-11-isoalkyloxy)propyl)derivatives C<sub>10</sub>-rich

74.06% water

#### Formulation G

5.36% benzyltrimethylammonium hydroxide

0.28% potassium hydroxide

10.0% tetramethylene sulfone

10.0% di(ethyleneglycol)butyl ether

0.10% oxirane, methyl-, polymer with oxirane, monb(octylphenyl)ether

0.08% 2-mercaptobenzimidazole

74.18% water,

#### Formulation H

benzyltrimethylammonium hydroxide, 40% aqueous solution	9.0 %
potassium hydroxide, 45% aqueous solution	0.6 %
N-methylmorpholine oxide, 50% aqueous solution	7.0 %
dinonylphenol ethoxylate, 7% aqueous solution	4.3 %
2-mercaptobenzimidazole	0.1 %
aminopropylmorpholine	20.0,%
water	59.02 %

#### Formulation I

benzyltrimethylammonium hydraxide, 40% aqueous solution	9.0 %
potassium hydroxide, 45% aqueous solution	0.6 %
N-methylmorpholine oxide, 50% aqueous solution	7.0 %
dinonylphenol ethoxylate, 7% aqueous solution	4.3 %
2-mercaptobenzimidazole	0.1 %
aminopropylmorpholine	15.0 %
water	64.02 %

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Formulation J	
benzyltrimethylammonium hydroxide, 40% aqueous potassium hydroxide, 45% aqueous solution N-methylmorpholine oxide, 50% aqueous solution dinonylphenol ethoxylate, 7% aqueous solution 2-mercaptobenzimidazole aminopropylmorpholine water	9.0 % 0.6 % 7.0 % 4.3 % 0.1 % 10.0 % 69.02 %
Formulation K	•
benzyltrimethylammonium hydroxide, 40% aqueous N-methylmorpholine oxide, 50% aqueous solution KOH, 45% aqueous solution 2-mercaptobenzimidizole dinonylphenol polyoxyethylene water	solution 13.4 % 7.0 % 0.6 % 0.08 % 0.3 % 78.62 %
Formulation L	
benzyltrimethylammonium hydroxide, 40% aqueous N-methylmorpholine oxide, 50% aqueous solution KOH, 45% aqueous solution 2-mercaptobenzimidizole dinonylphenol polyoxyethylene water	solution 13.4 % 7.0 % 1.2 % 0.08 % 0.3 % 78.02 %
Formulation M	
tetramethylammonium hydroxide, 25% aqueous solution N-methylmorpholine oxide, 50% aqueous solution KOH, 45% aqueous solution 2-mercaptobenzimidizole dinonylphenol polyoxyethylene water	tion 5.85 % 7.0 % 1.2 % 0.08 % 0.3 % 85.57 %
Formulation N	
tetramethylammonium hydroxide, 25% aqueous solution N-methylmorpholine oxide, 50% aqueous solution KOH, 45% aqueous solution 2-mercaptobenzimidizole dinonylphenol polyoxyethylene water	2.93 % 7.0 % 1.2 % 0.08 % 0.3 % 88.49 %
Formulation O	
benzyltrimethylammonium hydroxide, 40% aqueous N-methylmorpholine oxide, 50% aqueous solution KOH, 45% aqueous solution	solution 7.2 % 7.0 % 0.6 %

Formulation U

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2-mercaptobenzimidizole dinonylphenol polyoxyethylene water	0.08 % 0.3 % 84.82 %
Formulation P	
benzyltrimethylammonium hydroxide, 40% aqueous solution N-methylmorpholine oxide, 50% aqueous solution KOH, 45% aqueous solution 2-mercaptobenzimidizole dinonylphenol polyoxyethylene water	3.6 % 7.0 % 1.2 % 0.08 % 0.3 % 87.82 %
Formulation Q	
benzyltrimethylammonium hydroxide, 40% aqueous solution N-methylmorpholine oxide, 50% aqueous solution KOH, 45% aqueous solution 2-mercaptobenzimidizole dinonylphenol polyoxyethylene water	3.6 % 7.0 % 0.6 % 0.08 % 0.3 % 88.42 %
Formulation R	
benzyltrimethylammonium hydroxide, 40% aqueous solution N-methylmorpholine oxide, 50% aqueous solution KOH, 45% aqueous solution 2-mercaptobenzimidizole dinonylphenol polyoxyethylene water	7.2 % 7.0 % 0.3 % 0.08 % 0.3 % 85.12 %,
Formulation S	
benzyltrimethylammonium hydroxide, 40% aqueous solution Potassium hydroxide, 45% aqueous solution 2-mercaptobenzimidazole methyldiethanolamine phosphoric acid (86 %) 3-amino-5-mercapto-1,2,4-triazole water	22.26 % 0.6 % 0.08 % 2.33 % 1.69 % 1.0 % 72.04 %
Formulation T	
benzyltrimethylammonium hydroxide, 40% aqueous solution Potassium hydroxide, 45% aqueous solution 2-mercaptobenzimidazole methyldiethanolamine phosphoric acid (86 %) 4-methyl-2-phenyl-imidazole water	22.26 % 0.6 % 0.08 % 2.33 % 1.69 % 1.0 % 72.04 %

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	-turing 22	2.26 %
benzyltrimethylammonium hydroxide, 40% aqueous s	olution 22	6%
Potassium hydroxide, 45% aqueous solution		08 %
2-mercaptobenzimidazole		33 %
methyldiethanolamine		69 %
phosphoric acid (86 %)		0%
2-mercaptothiazoline		2.04 %
water		
Formulation V		
benzyltrimethylammonium hydroxide, 40% aqueous s	A16500	2.26 %
Potassium hydroxide, 45% aqueous solution	v.	6%
2-mercaptobenzimidazole		08 %
methyldiethanolamine		33 %
phosphoric acid (86 %)		.69 %
8-hydroxyquinoline		0 %
water	7.	2.04 %
Formulation W		
benzyltrimethylammonium hydroxide, 40% aqueous s	colution 2	2.26 % ·
Potassium hydroxide, 45% aqueous solution		.6%
2-mercaptobenzimidazole	0	.08 %
methyldiethanolamine	2	.33 %
phosphoric acid (86 %)	1	.69 %
1-phenyl-2-tetrazoline-5-thione	Ι	.0 %
water	7	2.04 %
W 2005		
Formulation X		
benzyltrimethylammonium hydroxide, 40% aqueous		2.26 %
Potassium hydroxide, 45% aqueous solution	U	.6%
2-mercaptobenzimidazole	-	.08 % .33 %
methyldiethanolamine		.69 %
phosphoric acid (86 %)		.0 %
gallic acid	-	2.04 %
water .		2.04 /0
Formulation Y		
benzyltrimethylammonium hydroxide, 40% aqueous		2.26 %
Potassium hydroxide, 45% aqueous solution	· ·	.6 %
2-mercaptobenzimidazole	_	.08 %
methyldiethanolamine	2	.33 %
phospharic scid (86 %)		.69 %
salicylic acid	_	.0%
water	7	2.04 %
Formulation Z		
benzyltrimethylammonium hydroxide, 40% aqueous	solution 2	2.26 %
Potassium hydroxide, 45% aqueous solution		0.6 %
2-mercaptobenzimidazole		.08 %
e-marchanessan		

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methyldiethanolamine	2.33 %
phosphoric acid (86 %)	1.69 %
ascorbic acid	1.0 %
water	72.04 %
Formulation A <sup>2</sup>	
benzyltrimethylammonium hydroxide, 40% aqueous s	olution 7.2 %
Potassium hydroxide, 45% aqueous solution	0.6 %
2-mercaptobenzimidazole	0.08 %
aminopropyl morpholine	<b>10 %</b> .
4-methyl-2-phenyl-imidazolc	· 1.0 %
water	81.12 %
Formulation B <sup>2</sup>	
benzyltrimethylammonium hydroxide, 40% aqueous s	olution 7.2 %
Potassium hydroxide, 45% aqueous solution	0.6 %
2-mercaptobenzimidazole	0.08 %
aminopropyl morpholine	<b>10 %</b> .
4-methyl-2-phenyl-imidazole	0.5 %
water	81.62 %
Formulation C <sup>2</sup>	
	olution 7.2 %
benzyltrimethylammonium hydroxide, 40% aqueous s	0.6 %
Potassium hydroxide, 45% aqueous solution	0.08 %
2-mercaptobenzimidazole	10 %
aminopropyl morpholine	1.0 %
4-methyl-2-phenyl-imidazole	81.02 %
water	0.1 %
dinonylphenol polyoxyethylene	V.1 /0

wherein said cleaning composition is useful for removing photoresist and/or sacrificial antireflective coating (SARC) materials from a substrate having such material(s) thereon.

- 8. (Withdrawn) A cleaning composition including an active cleaning combination (ACC), wherein said ACC consists of a strong base in combination with an oxidant and said cleaning composition is useful for removing photoresist analor sacrificial anti-reflective coating (SARC) materials from a substrate having such material(s) thereon.
- 9. (Withdrawn) The cleaning composition of claim 8, which includes an aqueous solution of at least one oxidant, a strong base, optionally a chelator and optionally a co-solvent and/or a surfactant.

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- 10. (Original) The cleaning composition of claim 1, wherein the ACC comprises potassium hydroxide.
- 11. (Withdrawn) The cleaning composition of claim 8, including the following components:
  - 0.1-30 wt % strong base;
  - 0.01-30 wt % oxidant;
  - 0-10 wt % chelator;
  - 0-5 wt % surfactant;
  - 0-50 wt % co-solvent; and
  - 20-98.9 wt % deionized water,

wherein percentages of the components are percentages by weight, based on total weight of the composition, and wherein the total of the weight percentages of such components of the composition does not exceed 100 weight %.

- 12. (Withdrawn) The cleaning composition of claim 11, wherein the strong base comprises a base species selected from the group consisting of potassium hydroxide and alkylammonium hydroxides and choline hydroxide.
- 13. (Withdrawn) The cleaning composition of claim 8, wherein the oxidant comprises an oxidant species selected from the group consisting of hydrogen peroxide, amine-N-oxides, perborate salts, persulfate salts, and combinations of two or more of the foregoing.
- 14. (Previously Presented) The cleaning composition of claim 1, further comprising a chelator.
- 15. (Original) The cleaning composition of claim 14, wherein the chelator comprises a chelator species selected from the group consisting of: triazoles; triazoles substituted with substituent(s) selected from the group consisting of  $C_1$ - $C_0$  alkyl, amino, thiol, mercapto, imino, carboxy and nitro; thiazoles; tetrazoles; imidazoles, phosphates; thiols; azines; glycerols; amino acids; carboxylic acids; alcohols; amides; and quinolines.
- 16. (Original) The cleaning composition of claim 14, wherein the chelator comprises a chelator species selected from the group consisting of: 1,2,4-triazole; benzotriazole; tolyltriazole; 5-phenyl-benzotriazole; 5-nitro-benzotriazole; 1-anino-1,2,4-triazole; hydroxybenzotriazole; 2-

(5-amino-pentyl)-benzotriazole; 1-amino-1,2,3-triazole; 1-amino-5-methyl-1,2,3-triazole; 3-amino-1,2,4-triazole; 3-mercapto-1,2,4-triazole; 3-isopropyl-1,2,4-triazole; 5-phenylthiol-benzotriazole; halo-benzotriazoles wherein halo is selected from the group consisting of F, Cl, Br and I; naphthotriazole; 2-mercaptobenzoimidizole 2-mercaptobenzothiazole; 5-aminotetrazole; 5-amino-1,3,4-thiadiazole-2-thiol; 2,4-diamino-6-methyl-1,3,5-triazine; thiazole; triazine; methyltetrazole; 1,3-dimethyl-2-imidazolidinone; 1,5-pentamethylenetetrazole; 1-phenyl-5-mercaptobenzimidazole; 4-methyl-4H-1,2,4-triazole-3-thiol; 5-amino-1,3,4-thiadiazole-2-thiol; benzothiazole; trritolyl phosphate; indiazole; guanine; adenine; glycerol; thioglycerol; nitrilotriacetic acid; salicylamide; iminodiacetic acid; benzoguanamine; melamine; thiocyranuric acid; anthranilic acid; 8-hydroxyquinoline; 5-carboxylic acid-benzotriazole; 3-mercaptopropanol; boric acid; and iminodiacetic acid.

- 17. (Previously Presented) The composition of claim 1, further comprising a surfactant.
- 18. (Original) The composition of claim 17, wherein the surfactant comprises a surfactant species selected from the group consisting of: fluoroalkyl surfactants; polyethylene glycols; polypropylene glycols; polypropylene glycol ethers; polypropylene glycol ethers; carboxylic acid salts; dodecylbenzenesulfonic acid and salts thereof; polyacrylate polymers; dinonylphenyl polyoxyethylene; silicone polymers; modified silicone polymers; acetylenic diols; modified acetylenic diols, alkylammonium salts; modified alkylammonium salts; and combinations of two or more of the foregoing.
- 19. (Previously Presented) The composition of claim 1, further comprising a co-solvent.
- 20. (Original) The composition of claim 19, wherein the co-solvent comprises a co-solvent species selected from the group consisting of: amines; glycols; glycol ethers; polyglycol ethers; and combinations of two or more of the foregoing.
- 21. (Original) The composition of claim 19, wherein the co-solvent comprises a co-solvent species selected from the group consisting of: dimethyldiglycolamine; 1,8-diazabicyclo[5.4.0]undecene; aminopropylmorpholine; triethanolamine; methylethanolamine; diethylene glycol; propylene glycol; neopentyl glycol; hydroxyethylmorpholine; aminopropylmorpholine; di(ethylene glycol)monoethyl ether; di(propylene glycol)propyl ether;

ethylene glycol phenyl ether; di(propylene glycol) butyl ether; butyl carbitol; polyglycol ethers; and combinations of two or more of the foregoing.

22. (Withdrawn) The cleaning composition of claim 8, including:

0.1-30 wt % strong base

2-30 wt % oxidant

0-10 wt % chelator

0-5 wt % surfactant

20-98 wt % deionized water

wherein percentages of the components are percentages by weight, based on total weight of the composition, and wherein the total of the weight percentages of such components of the composition does not exceed 100 weight %.

23. (Withdrawn) The cleaning composition of claim 8, selected from the group consisting of Formulations D<sup>2</sup>-R<sup>2</sup>, wherein all percentages are by weight, based on the total weight of the formulation:

Formul	ation	m
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tetramethylammonium hydroxide, 25% aqueous solution  N-methylmorpholine oxide, 50% aqueous solution  dinonylphenol ethoxylate, 7% aqueous solution  3-amino-5-mercapto-1,2,4-triazole  water  73.9 %  Formulation E <sup>2</sup>
dinonylphenol ethoxylate, 7% aqueous solution 3-amino-5-mercapto-1,2,4-triazole water  4.3 % 0.1 % 73.9 %
3-amino-5-mercapto-1,2,4-triazole 0.1 % water 73.9 %
water 73.9 %
Formulation B <sup>2</sup>
tetramethylammonium hydroxide, 25% aqueous solution 14.7%
N-methylmorpholine oxide, 50% aqueous solution 7.0 %
dinonylphenol ethoxylate, 7% aqueous solution 4.3 %
ammonium tetrathiomolybdate   0.1 %
water 73.9 %
Formulation F <sup>2</sup>
tetramethylammonium hydroxide, 25% aqueous solution 14.7%
N-methylmorpholine oxide, 50% aqueous solution 7.0 %
dinonylphenol ethoxylate, 7% aqueous solution . 4.3 %
2-mercaptobenzimidazole 0.1 %
aminopropylmorpholine 20.0 %
water : 53.9 %

Formulation G <sup>2</sup>	
tetramethylammonium hydroxide, 25% aqueous solut	tion 14.7 %
N-methylmorpholine oxide, 50% aqueous solution	7.0 %
dinonylphenol ethoxylate, 7% aqueous solution	4.3 %
2-mercaptobenzimidazole	0.1 %
N-ethylmorpholine	20.0 %
water	53.9 %
i	
Formulation H <sup>2</sup>	
tetramethylammonium hydroxide, 25% aqueous solla	tion 14.7 %
N-methylmorpholine oxide, 50% aqueous solution	7.0 %
dinonylphenol ethoxylate, 7% aqueous solution	4.3 %
2-mercaptobenzimidazole	0.1 %
aminoethylpiperidine	20.0 %
water	53.9 %
	•
Formulation I <sup>2</sup>	
tetramethylammonium hydroxide, 25% aqueous solu	tion 14.7 %
N-methylmorpholine oxide, 50% aqueous solution	7.0 %
dinonylphenol ethoxylate, 7% aqueous solution	4.3 %
3-amino-5-1,2,4-triazole	0.1 %
aminopropylmorpholine	20.0 %
water	53.9 %
Formulation J <sup>2</sup>	
tetramethylammonium hydroxide, 25% aqueous solu	tion 14.7 %
N-methylmorpholine oxide, 50% aqueous solution	7.0 %
dinonylphenol ethoxylate, 7% aqueous solution	4.3 %
3-amino-5-1,2,4-triazole	0.1 %
aminopropylmorpholine	10.0 %
water	63.9 %
!	
Formulation K <sup>2</sup>	
tetramethylammonium hydroxide, 25% aqueous solu	tion 14.7 %
N-methylmorpholine oxide, 50% aqueous solution	7.0 %
dinonylphenol ethoxylate, 7% aqueous solution	4.3 %
2-mercaptobenzimidazole	0.1 %
aminopropylmorpholine	20.0 %
water	53.9 %
	•
Formulation L <sup>2</sup>	
tetramethylammonium hydroxide, 25% aqueous solu	tion 14.7 %
N-methylmorpholine oxide, 50% aqueous solution	7.0 %
dinonylphenol ethoxylate, 7% aqueous solution	4.3 %
2-mercaptobenzimidazole	0.1 %

•	
aminopropylmorpholine	10.0 %
water	63.9 %
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Formulation M <sup>2</sup>	
tetramethylammonium hydroxide, 25% aqueous solution	4.0 %
hydrogen peroxide, 30% aqueous solution	2.0 %
5-aminotetrazole	0.1 %
water	93.9 %
Formulation N <sup>2</sup>	
	4.0.04
tetramethylammonium hydroxide, 25% aqueous solution	4.0 %
hydrogen peroxide, 30% aqueous solution	2.0 %
2,4-diamino-6-methyl-1,3,5-triazine	0.1 % 93.9 %
water	93.9 %
Formulation O <sup>2</sup>	
tetramethylammonium hydroxide, 25% aqueous solution	4.0 %
hydrogen peroxide, 30% aqueous solution	· 2.0 %
5-amino-1,3,4-thiadiazole-2-thiol	0.1 %
Water	93.9 %
water ,	
Formulation P <sup>2</sup>	
tetramethylammonium hydroxide, 25% aqueous solution	4.0 %
hydrogen peroxide, 30% aqueous solution	2.0 %
1,2,4-triazole	0.1 %
water	93.9 %
Formulation Q <sup>2</sup>	
tetramethylammonium hydroxide, 25% aqueous solution	4.0 %
hydrogen peroxide, 30% aqueous solution	2.0 %
2,4-dihydroxy-6-methylpyrimidine	0.1 %
water	93.9 %
Formulation R <sup>2</sup>	٠.
automathulanungaine berkenvida 25% nersawa salitien	4.0 %
tetramethylammonium hydroxide, 25% aqueous solution	2.0 %
hydrogen peroxide, 30% aqueous solution   8-hydroxyquinoline	0.1 %
	93.9 %.
water	73.7 /0.

24. (Withdrawn) A method of removing photoresist and/or SARC material from a substrate having said material thereon, said method comprising contacting the substrate with a cleaning composition for sufficient time to at least partially remove said material from the substrate, wherein the cleaning composition includes an active cleaning combination (ACC) consisting of a

quaternary base in combination with at least one of alkali and alkaline earth base.

- 25. (Withdrawn) The method of claim 24, wherein the substrate comprises a semiconductor device structure.
- 26. (Withdrawn) The method of claim 24, wherein the material comprises photoresist.
- 27. (Withdrawn) The method of claim 24, wherein the material comprises SARC material.
- 28. (Withdrawn) The method of claim 27, wherein the SARC material has been applied to a semiconductor device structure to minimize reflectivity variations during photolithographic patterning on the semiconductor device structure.
- 29. (Withdrawn) The method of claim 24, wherein said contacting is carried out for a time of from about 10 to about 45 minutes.
- 30. (Withdrawn) The method of claim 24, wherein said contacting is carried out at temperature in a range of from about 50°C to about 80°C.
- 31. (Withdrawn) The method of claim 24, wherein the composition is devoid of hydroxylamine therein.
- 32. (Cancelled)
- 33. (Withdrawn) The method of claim 24, wherein the composition comprises the following components:
  - 0.1 40.0 weight % organic quaternary base,
  - 0.01-5 weight % alkali or alkaline earth base;
  - 0-80 weight % solvent(s) and/or amine(s);
  - 0-5 weight % surfactant;
  - 0 10 weight % chelator/passivation agent; and
  - 0 98 weight % water,

wherein percentages of the components are percentages by weight, based on total weight of the composition, and wherein the total of the weight percentages of such components of the

composition does not exceed 100 weight %.

- 34. (Withdrawn) The method of claim 24, wherein the composition includes at least one additional ingredient selected from the group consisting of stabilizers, dispersants, anti-oxidants, fillers, penetration agents, adjuvants, additives, fillers, and excipients.
- 35. (Withdrawn) The method of claim 24, wherein the composition comprises the following components:
  - 2-15 weight % organic quaternary base;
  - ~0.01-2 weight % alkali or alkaline earth base;
  - 0-50 weight % solvent(s) and/or amine(s);
  - ~0.01-2 weight % surfactant;
  - 0-5 weight % chelator/passivation agent; and
  - 40 95 weight % water,

wherein percentages of the components are percentages by weight, based on total weight of the composition, and wherein the total of the weight percentages of such components of the composition does not exceed 100 weight %.

36. (Withdrawn) A method of removing photoresist and/or SARC material from a substrate having said material thereon, said method comprising contacting the substrate with a cleaning composition for sufficient time to at least partially remove said material from the substrate, wherein the cleaning composition is selected from the group consisting of Formulations A-C<sup>2</sup>, wherein all percentages are by weight, based on the total weight of the formulation:

#### Formulation A

5.36% benzyltrimethylammonium hydroxide
0.28% potassium hydroxide
3.0% 4-methylkmorpholine N-oxide
0.30% polyoxyethylene(150) dinonylphenyl ether
0.08% 2-mercaptobenzimidazole
91.0% water

#### Formulation B

5.36% benzyltrimethylammonium hydroxide
0.28% potassium hydroxide
3.0% 4-methylmorpholine N-oxide
0.30% polyoxyethylene(150) dinonylphenyl ether

0.20% 5-amino-1,3,4-thiadiazole-2-thiol 90.86% water

#### Formulation C

3.60% benzyltrimethylammonium hydroxide
0.27% potassium hydroxide
3.5% 4-methylmorpholine N-oxide
15.0% 4-(3-aminopropyl)morpholine
0.30% polyoxyethylene(150) dinonylphenyl ether
0.08% 2-mercaptobenzimidazole
77.25% water

#### Formulation D

5.36% benzyltrimethylammonium hydroxide
0.28% potassium hydroxide
20.0% dimethyl sulfoxide
0.08% 2-mercaptobenzimidazole
74.28% water

#### Formulation E

5.36% benzyltrimethylammonium hydroxide
0.28% potassium hydroxide
10.0% tetramethylene sulfone
0.30% oxirane, methyl-, polymer with oxirane, ether with 2,2'-(oxidoimino)bis(ethanol) (2:1),
N(-3(C9-11-isoalkyloxy)propyl)derivatives C<sub>10</sub>-rich
0.08% 2-mercaptobenzimidazole
83.98% water

#### Formulation F

5.36% benzyltrimethylammonium hydroxide
0.28% potassium hydroxide
10.0% di(ethyleneglycol)butyl ether
10.0% 2-(2-dimethylamino)ethoxy)ethanol
0.30% oxirane, methyl-, polymer with oxirane, ether with 2,2'-(oxidoimino)bis(ethanol) (2:1),
N(-3(C9-11-isoalkyloxy)propyl)derivatives,
74.06% water

#### Formulation G

5.36% benzyltrimethylammonium hydroxide
0.28% potassium hydroxide
10.0% tetramethylene sulfone
10.0% di(ethyleneglycol)butyl ether
0.10% oxirane, methyl-, polymer with oxirane, mono(octylphenyl)ether
0.08% 2-mercaptobenzimidazole
74.18% water,

Formulation H	
benzyltrimethylammonium hydroxide, 40% aqueous solution	9.0 %
potassium hydroxide, 45% aqueous solution	0.6 %
N-methylmorpholine oxide, 50% aqueous solution	7.0 %
dinonylphenol ethoxylate, 7% aqueous solution	4.3 %
2-mercaptobenzimidazole	0.1 %
aminopropylmorpholine	20.0 %
water	59.02 %
Formulation I	
benzyltrimethylammonium hydroxide, 40% aqueous solution	9.0 %
potasaium hydroxide, 45% aqueous solution	0.6 %
N-methylmorpholine oxide, 50% aqueous solution	7.0 %
dinonylphenol ethoxylate, 7% aqueous solution	4.3 %
2-mercaptobenzimidazole	0.1 %
aminopropylmorpholine	15.0 %
water	64.02 %
Families 5	•
Formulation J	0.00
benzyltrimethylammonium hydroxide, 40% aqueous solution	9.0 % 0.6 %
potassium hydroxide, 45% aqueous solution N-methylmorpholine oxide, 50% aqueous solution	7.0 %
dinonylphenol ethoxylate, 7% aqueous solution	4.3 %
2-mercaptobenzimidazole	0.1 %
aminopropylmorpholine	10.0 %
water water	69.02 %
, , , , , , , , , , , , , , , , , , ,	V/2 //
Formulation K	
benzyltrimethylammonium hydroxide, 40% aqueous solution	13.4 %
N-methylmorpholine oxide, 50% aqueous solution	7.0 %
KOH, 45% aqueous solution	0.6 %
2-mercaptobenzimidizole	0.08 %
dinonylphenol polyoxyethylene	0.3 %
water	78.62 %
Pormulation L	
	12.40/
benzyltrimethylammonium hydroxide, 40% aqueous solution	13.4 % 7.0 %
N-methylmorpholine oxide, 50% aqueous solution	7.0 %
KOH, 45% aqueous solution	1.2 % 0.08 %
2-mercaptobenzimidizole dinonylphenol polyoxyethylene	0.08 %
water	78.02 %
TT GO DAGE	10.00 /0
Formulation M	
tetramethylammonium hydroxide, 25% aqueous solution	5.85 %
wanners ammented filth average or 14 selection activing	J.05 /0

N-methylmorpholine oxide, 50% aqueous solution . KOH, 45% aqueous solution . 2-mercaptobenzimidizole . dinonylphenol polyoxyethylene . water .	7.0 % 1.2 % 0.08 % 0.3 % 85.57 %
Formulation N	
tetramethylammonium hydroxide, 25% aqueous solution N-methylmorpholine oxide, 50% aqueous solution KOH, 45% aqueous solution 2-mercaptobenzimidizole dinonylphenol polyoxyethylene water	2.93 % 7.0 % 1.2 % 0.08 % 0.3 % 88.49 %
Formulation O	
benzyltrimethylammonium hydroxide, 40% aqueous solution N-methylmorpholine oxide, 50% aqueous solution KOH, 45% aqueous solution 2-mercaptobenzimidizole dinonylphenol polyoxyethylene water	7.2 % 7.0 % 0.6 % 0.08 % 0.3 % 84.82 %
Formulation P	
benzyltrimethylammonium hydroxide, 40% aqueous solution N-methylmorpholine oxide, 50% aqueous solution KOH, 45% aqueous solution 2-mercaptobenzimidizole dinonylphenol polyoxyethylene water	3.6 % 7.0 % 1.2 % 0.08 % 0.3 % 87.82 %
Formulation Q	
benzyltrimethylammonium hydroxide, 40% aqueous solution N-methylmorpholine oxide, 50% aqueous solution KOH, 45% aqueous solution 2-mercaptobenzimidizole dinonylphenol polyoxyethylene water	3.6 % 7.0 % 0.6 % 0.08 % 0.3 % 88.42 %
Formulation R	•
benzyltrimethylammonium hydroxide, 40% aqueous solution N-methylmorpholine oxide, 50% aqueous solution KOH, 45% aqueous solution 2-mercaptobenzimidizole dinonylphenol polyoxyethylene water	7.2 % 7.0 % 0.3 % 0.08 % 0.3 % 85.12 %,

•	
Formulation S	
benzyltrimethylanimonium hydroxide, 40% aqueous solution Potassium hydroxide, 45% aqueous solution 2-mercaptobenzimidazole methyldiethanolamine phosphoric acid (86 %) 3-amino-5-mercapto-1,2,4-triazole water	22.26 % 0.6 % 0.08 % 2.33 % 1.69 % 1.0 % 72.04 %
Formulation T	
benzyltrimethylammonium hydroxide, 40% aqueous solution Potassium hydroxide, 45% aqueous solution 2-mercaptobenzimidazole methyldiethanolamine phosphoric acid (86 %) 4-methyl-2-phenyl-imidazole water	22.26 % 0.6 % 0.08 % 2.33 % 1.69 % 1.0 % 72.04 %
Formulation U	
benzyltrimethylammonium hydroxide, 40% aqueous solution Potassium hydroxide, 45% aqueous solution 2-mercaptobenzimidazole methyldiethanolamine phosphoric acid (86 %) 2-mercaptothiazoline water	22.26 % 0.6 % 0.08 % 2.33 % 1.69 % 1.0 % 72.04 %
Formulation V	•
benzyltrimethylammonium hydroxide, 40% aqueous solution Potassium hydroxide, 45% aqueous solution 2-mcrcaptobenzimidazole methyldiethanolamine phosphorie acid (86 %) 8-hydroxyquinoline water	22.26 % 0.6 % 0.08 % - 2.33 % 1.69 % 1.0 % 72.04 %
Formulation W	
benzyltrimethylammonium hydroxide, 40% aqueous solution Potassium hydroxide, 45% aqueous solution 2-mercaptobenzimidazole methyldiethsnolamine phosphoric acid (86%) 1-phenyl-2-tetrazoline-5-thions water	22.26 % 0.6 % 0.08 % 2.33 % 1.69 % 1.0 % 72.04 %
Formulation X	
benzyltrimethylammonium hydroxide, 40% aqueous solution Potassium hydroxide, 45% aqueous solution	22.26 % 0.6 %

2-mercaptobenzimidazole	0.08 %	
methyldiethanolamine (	2.33 %	
phosphoric acid (86 %)	1.69 %	
gallic acid	1.0 %	
water	72.04 %	, D
Formulation Y		
benzyltrimethylammonium hydroxide, 40% aqueou	s solution 22.26 %	•
Potassium hydroxide, 45% aqueous solution	0.6 %	
2-mercaptobenzimidazole	0.08 %	
methyldiethanolamine j	2.33 %	
phosphoric acid (86 %)	1.69 %	
salicylic acid	1.0 %	
water	72.04 %	
Remulation 7	<del> </del>	
Formulation Z		
benzyltrimethylammonium hydroxide, 40% aqueou		•
Potassium hydroxide, 45% aqueous solution	0.6 %	
2-mercaptobenzimidazole	· 0.08 %	
methyldiethanolamine	2.33 %	
phosphoric acid (86 %)	1.69 %	
ascorbic acid	1.0 %	
water	72.04 %	1
Formulation A <sup>2</sup>	}	
benzyltrimethylammonium hydroxide, 40% aqueout	720/	
Potassium hydroxide, 45% aqueous solution		
2-mercaptobenzimidazole	0.6 % 0.08 %	
aminopropyl morpholine	10 %	
4-methyl-2-phenyl-imidazole	1.0 %	
water	81.12%	
	01.12 %	
Formulation B <sup>2</sup>		
benzyltrimethylammonium hydroxide, 40% aqueous	solution 7.2 %	
Potassium hydroxide, 45% aqueous solution	0.6 %	
2-mercaptobenzimidazole	0.08 %	
aminopropyl morpholine .	• 10 %	
4-methyl-2-phenyl-imidazole	0.5 %	
water	81.62 %	
Formulation C <sup>2</sup>	•	
benzyltrimethylammonium hydroxide, 40% aqueous		
Potassium hydroxide, 45% aqueous solution	0.6 %	
2-mercaptobenzimidazole	0.08 %	
aminopropyl morpholine	10 %	
4-methyl-2-phenyl-imidazole	1.0 %	
water	81.02 %	
dinonylphenol polyoxyethylene	0.1 %.	

- 37. (Withdrawn) A method of removing photoresist and/or SARC material from a substrate having said material thereon, said method comprising contacting the substrate with a cleaning composition for sufficient time to at least partially remove said material from the substrate, wherein the cleaning composition includes the active cleaning combination (ACC) of claim 8.
- 38. (Withdrawn) The method of claim 37, wherein the cleaning composition includes an aqueous solution of at least one oxidant, a strong base, optionally a chelator and optionally a co-solvent and/or a surfactant.
- 39. (Withdrawn) The method of claim 24, wherein the ACC comprises potassium hydroxide.
- 40. (Withdrawn) The method of claim 37, wherein the cleaning composition includes the following components:

0.1-30 wt % strong base;

0.01-30 wt % oxidant;

0-10 wt % chelstor;

0-5 wt % surfactant;

0-50 wt % co-solvent; and

20-98.9 wt % deionized water,

wherein percentages of the components are percentages by weight, based on total weight of the composition, and wherein the total of the weight percentages of such components of the composition does not exceed 100 weight %.

- 41. (Withdrawn) The method of claim 40, wherein the strong base comprises a base species selected from the group consisting of potassium hydroxide and alkylammonium hydroxides and choline hydroxide.
- 42. (Withdrawn) The method of claim 37, wherein the oxidant comprises an oxidant species selected from the group consisting of hydrogen peroxide, amine-N-oxides, perborate salts, persulfate salts, and combinations of two or more of the foregoing.
- 43. (Withdrawn) The method of claim 24, wherein the cleaning composition further comprises a chelator.

- 44. (Withdrawn) The method of claim 43, wherein the chelator comprises a chelator species selected from the group consisting of: triazoles; triazoles substituted with substituent(s) selected from the group consisting of C<sub>1</sub>-C<sub>4</sub> alkyl, amino, thiol, mercapto, imino, carboxy and nitro; thiszoles; tetrazoles; imidazoles; phosphates; thiols; azines; glycerols; amino acids; carboxylic acids; alcohols; amides; and quinolines.
- (Withdrawn) The method of claim 43, wherein the chelator comprises a chelator species 45. selected from the group consisting of: 1,2,4-triazole; benzotriazole; tolyltriazole; 5-phenylbenzotriazole; 5-nitro-benzotriazole; 1-amino-1,2|4-triazole; hydroxybenzotriazole; 2-(5-aminopentyl)-benzotriazole; 1-amino-1,2,3-triazole; 1-amino-5-methyl-1,2,3-triazole; 3-amino-1,2,4triazole; 3-mercapto-1,2,4-triazole; 3-isopropyl-1,2,4-triazole; 5-phenylthiol-benzotriazole; halobenzotriazoles wherein halo is selected from the group consisting of F, Cl, Br and I; naphthotriazole; 2-mercaptobenzoimidizole; 2-mercaptobenzothiazole; 5-aminotetrazole; 5thiazole: triazine: 2,4-diamino-6-methyl-1,3,5-triazine; amino-1,3,4-thiadiazole-2-thiol; methyltetrazole; 1,3-dimethyl-2-imidazolidinone; 1,5-pentamethylenetetrazole; 1-phenyl-5mercaptotetrazole; diaminomethyltriazine; mercaptobenzothiazole; imidazoline mercantobenzimidazole; 4-methyl-4H-1,2,4-triazole-3-thiol; 5-amino-1,3,4-thiadiazole-2-thiol; benzothiazole; trritolyl phosphate; indiazole; guanine; adenine; glycerol; thioglycerol; nitrilotriacetic acid; salicylamide; iminodiacetic acid; benzoguanamine; melamine; thiocyranuric acid; anthranilic acid; 8-hydroxyquinoline; 5-carboxylic acid-benzotriazole; 3-mercaptopropanol; boric acid; and iminodiacetic acid.
- 46. (Withdrawn) The method of claim 24, wherein the cleaning composition further comprises a surfactant.
- 47. (Withdrawn) The method of claim 46, wherein the surfactant comprises a surfactant species selected from the group consisting of: fluoroalkyl surfactants; polyethylene glycols; polypropylene glycols; polypropylene glycol ethers; polypropylene glycol ethers; carboxylic acid salts; dodecylbenzenesulfonic acid and salts thereof; polyacrylate polymers; dinonylphenyl polyoxyethylene; silicone polymers; modified silicone polymers; acetylenic diols; modified acetylenic diols, alkylammonium salts; modified alkylammonium salts; and combinations of two or more of the foregoing.

- 48. (Withdrawn) The method of claim 24, wherein the cleaning composition further comprises a co-solvent.
- 49. (Withdrawn) The method of claim 48, wherein the co-solvent comprises a co-solvent species selected from the group consisting of: amines; glycols; glycol ethers; polyglycol ethers; and combinations of two or more of the foregoing.
- (Withdrawn) The method of claim 48, wherein the co-solvent comprises a co-solvent 50. dimethyldiglycolamine; consisting of: selected the group from diazabicyclo[5.4.0]undecene; aminopropylmorphbline; triethanolamine; methylethanolamine; glycol; hydroxyethylmorpholine; glycol; neopentyl glycol; propylene aminopropylmorpholine; di(ethylene glycol)mondethyl ether; di(propylene glycol)propyl ether; ethylene glycol phenyl ether; di(propylene glycol) butyl ether; butyl carbitol; polyglycol ethers; and combinations of two or more of the foregoing.
- 51. (Withdrawn) The method of claim 37, wherein the composition includes:

0.1-30 wt % strong base

2-30 wt % oxident

0-10 wt % chelator

0-5 wt % surfactant

20-98 wt % deionized water

wherein percentages of the components are percentages by weight, based on total weight of the composition, and wherein the total of the weight percentages of such components of the composition does not exceed 100 weight %.

52. (Withdrawn) The method of claim 37, wherein the cleaning composition is selected from the group consisting of Formulations D<sup>2</sup>-R<sup>2</sup>, wherein all percentages are by weight, based on the total weight of the formulation:

#### Formulation D<sup>2</sup>

tetramethylammonium hydroxide, 25% aqueous solution	14.7 %
N-methylmorpholine oxide, 50% aqueous solution	7.0 %
dinonylphenol ethoxylate, 7% aqueous solution	4.3 %
3-amino-5-mercapto-1,2,4-triazole	0.1 %
water .	73.9 %

Formulation E <sup>2</sup>	
n-methylammonium hydroxide, 25% aqueous solution N-methylmorpholine oxide, 50% aqueous solution dinonylphenol ethoxylate, 7% aqueous solution ammonium tetrathiomolybdate water	14.7 % 7.0 % 4.3 % 0.1 % 73.9 %
Formulation F <sup>2</sup>	
tetramethylammonium hydroxide, 25% aqueous solution N-methylmorpholine oxide, 50% aqueous solution dinonylphenol ethoxylate, 7% aqueous solution 2-mercaptobenzimidazole aminopropylmorpholine water	14.7 % 7.0 % 4.3 % 0.1 % 20.0 % 53.9 %
Formulation G <sup>2</sup>	
tetramethylammonium hydroxide, 25% aqueous solution N-methylmorpholine oxide, 50% aqueous solution dinonylphenol ethoxylate, 7% aqueous solution 2-mercaptobenzimidazole N-ethylmorpholine water	14.7 % 7.0 % 4.3 % 0.1 % 20.0 % 53.9 %
Formulation H <sup>2</sup>	
tetramethylammonium hydroxide, 25% aqueous solution N-methylmorpholine oxide, 50% aqueous solution dinonylphenol ethoxylate, 7% aqueous solution 2-mercaptobenzimidazole aminoethylpiperidine water	14.7 % 7.0 % 4.3 % 0.1 % 20.0 % 53.9 %
Formulation I <sup>2</sup>	
tetramethylammonium hydroxide, 25% aqueous solution N-methylmorpholine oxide, 50% aqueous solution dinonylphenol ethoxylate, 7% aqueous solution 3-amino-5-1,2,4-triazole aminopropylmorpholine water	14.7 % 7.0 % 4.3 % 0.1 % 20.0 % 53.9 %
Formulation J <sup>2</sup>	
tetramethylammonium hydroxide, 25% aqueous solution N-methylmorpholine oxide, 50% aqueous solution dinonylphenol ethoxylate, 7% aqueous solution 3-amino-5-1,2,4-triazole aminopropylmorpholine	14.7 % 7.0 % 4.3 % 0.1 % 10.0 %

	•
water	63.9 %
Formulation K <sup>2</sup>	
tetramethylammonium hydroxide, 25% aqueous solu	ntion 14.7 %
N-methylmorpholine oxide, 50% aqueous solution	7.0 %
dinonylphenol ethoxylate, 7% aqueous solution	4.3 %
2-mercaptobenzimidazole	0.1 %
aminopropylmorpholine	20.0 %
water	53.9 %
Formulation L <sup>2</sup>	
tetramethylammonium hydroxide, 25% aqueous solu	
N-methylmorpholine oxide, 50% aqueous solution	7.0 %
dinonylphenol ethoxylate, 7% aqueous solution	4.3 %
2-mercaptobenzimidazole	0.1 %
aminopropylmorpholine !	10.0 %
water	63.9 %
Formulation M <sup>2</sup>	
tetramethylammonium hydroxide, 25% aqueous solu	
hydrogen peroxide, 30% aqueous solution	2.0 %
5-aminotetrazole	0.1 %
water	93.9 %
Formulation N <sup>2</sup>	
tetramethylammonium hydroxide, 25% aqueous solu	tion 4.0 %
hydrogen peroxide, 30% aqueous solution	2.0 %
2,4-diamino-6-methyl-1,3,5-triazine	0.1 %
water ·	93.9 %
Formulation O <sup>2</sup>	
tetramethylammonium bydroxide, 25% aqueous solu	tion 4.0 %
hydrogen peroxide, 30% aqueous solution	2.0 %
5-amino-1,3,4-thiadiazole-2-thiol	0.1 %
water	93.9 %
Formulation P <sup>2</sup>	
tetramethylammonium hydroxide, 25% aqueous solu	tion 4.0 %
hydrogen peroxide, 30% aqueous solution	2.0 %
1,2,4-triazole	0.1 %
water	93.9 %
P1-4 02	
Formulation Q <sup>2</sup>	2
tetramethylammonium hydroxide, 25% aqueous solu	tion 4.0 %

	:	
hydrogen peroxide, 30% aqueous solution		2.0 %
2,4-dihydroxy-6-methylpyrimidine	1	0.1 %
water		93.9 %
	•	
Formulation R <sup>2</sup>		
	1.	
tetramethylammonium hydroxide, 25% aqueous s	solution	4.0 %
hydrogen peroxide, 30% aqueous solution	•	2.0 %
8-hydroxyquinoline	1	0.1 %
water		93.9 %.

- 53. (Previously Presented) The cleaning composition of claim 1, wherein the quaternary base comprises an organic quaternary ammonium base.
- 54. (Previously Presented) The cleaning composition of claim 1, wherein the quaternary base comprises benzyltrimethylammonium hydroxide.
- 55. (Previously Presented) The cleaning composition of claim 1, wherein the ACC comprises benzyltrimethylammonium hydroxide and potassium hydroxide.
- 56. (Previously Presented) The cleaning composition of claim 19, wherein the co-solvent comprises a glycol ether.
- 57. (Previously Presented) The cleaning composition of claim I comprising benzyltrimethylammonium hydroxide; potassium hydroxide; tetramethylene sulfone; di(ethyleneglycol)butyl ether; oxirane, methyl-, polymer with oxirane, mono(octylphenyl)ether; 2-mercaptobenzimidazole; and water.
- 58. (Previously Presented) A method of making a semiconductor device comprising contacting the substrate with the cleaning composition of claim 1 for sufficient time to at least partially remove said material from the substrate.
- 59. (Previously Presented) The cleaning composition of claim 1, further comprising exident.

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